

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	70	tseng.in. and frame.ti.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/12/08 14:48
S2	2	tseng.in. and frame.ti. and negative adj pressure	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/12/08 14:49
S3	5	tseng.in. and frame.ti. and chip with substrate	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/12/08 14:49
S4	113	(frame ring spacer) near2 (around surround) with (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/12/08 14:55
S5	69	(frame ring spacer) near2 (around surround) with (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board)	USPAT; EPO; JPO	OR	ON	2005/12/08 15:02
S6	35	(frame ring spacer damp interposer) near2 (around surround) with (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid) and (vacuum suction sucking (negative adj1 pressure))	USPAT; EPO; JPO	OR	ON	2005/12/12 11:26
S9	6	"29"/\$.ccls. and (frame ring spacer damp interposer) with (around surround) with (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid) and (vacuum suction sucking (negative adj1 pressure))	USPAT; EPO; JPO	OR	ON	2005/12/08 15:22
S11	59	"257"/\$.ccls. and (frame ring spacer damp interposer) with (around surround) with (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid) and (vacuum suction sucking (negative adj1 pressure))	USPAT; EPO; JPO	OR	ON	2005/12/08 15:29
S13	28	"438"/\$.ccls. and (frame ring spacer damp interposer) with (around surround) with (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid) and (vacuum suction sucking (negative adj1 pressure))	USPAT; EPO; JPO	OR	ON	2005/12/08 15:46

S14	6	"361"/\$.ccls. and (frame ring spacer damp interposer) with (around surround) with (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid) and (vacuum suction sucking (negative adj1 pressure))	USPAT; EPO; JPO	OR	ON	2005/12/08 15:47
S15	6	"174"/\$.ccls. and (frame ring spacer damp interposer) with (around surround) with (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid) and (vacuum suction sucking (negative adj1 pressure))	USPAT; EPO; JPO	OR	ON	2005/12/08 15:48
S16	88	(frame ring spacer damp interposer) with (around surround) with (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid) and (vacuum suction sucking (negative adj1 pressure))	USPAT; EPO; JPO	OR	ON	2005/12/08 16:06
S17	31	(frame ring spacer damp interposer) with (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid) and negative adj1 pressure and (around surround)	USPAT; EPO; JPO	OR	ON	2005/12/08 16:05
S18	24	(frame ring spacer damp interposer) with (around\$3 surround\$3) with (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid plate) and (vacuum suction atmosphere sucking (negative adj1 pressure)) and (cmos cis (chip near2 sensor))	USPAT; EPO; JPO	OR	ON	2005/12/08 16:22
S23	24	("4523102").URPN.	USPAT	OR	ON	2005/12/08 16:16
S25	1	(frame ring spacer damp interposer) with (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid plate) and (vacuum suction atmosphere sucking (negative adj1 pressure)) with (attach\$3 solidif\$4) same ultraviolet near2 light	USPAT; EPO; JPO	OR	ON	2005/12/08 16:24
S26	4	(frame ring spacer damp interposer) and (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid plate) and (vacuum suction atmosphere sucking (negative adj1 pressure)) with (attach\$3 solidif\$4) same ultraviolet near2 light	USPAT; EPO; JPO	OR	ON	2005/12/08 16:25

S27	1	(frame ring spacer damp interposer) and (chip ic semiconductor) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid plate) and (vacuum suction atmosphere sucking (negative adj1 pressure)) with (attach\$3 mounting) and solidif\$4 with ultraviolet near2 light	USPAT; EPO; JPO	OR	ON	2005/12/08 16:28
S29	8	(frame ring spacer damp interposer) and (chip ic semiconductor cis cmos) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid plate) and (vacuum suction atmosphere sucking (negative adj1 pressure)) with (attach\$3 mounting) and solidif\$4 with light	USPAT; EPO; JPO	OR	ON	2005/12/08 16:32
S30	4	solidif\$4 with (frame ring spacer damp interposer) and (chip ic semiconductor cis cmos) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid plate) and (vacuum suction atmosphere sucking (negative adj1 pressure)) with (attach\$3 mounting)	USPAT; EPO; JPO	OR	ON	2005/12/08 16:38
S31	311	(seal\$4 solidif\$4) with (frame ring spacer damp interposer) and (chip ic semiconductor cis cmos) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid plate) same (vacuum suction atmosphere sucking (negative adj1 pressure)) and wafer	USPAT; EPO; JPO	OR	ON	2005/12/08 17:14
S33	52	("4169273" "4291815" "4352449" "4654622" "4701424" "4752694" "5010251" "5021663" "5082162" "5196377" "5220188" "5260225" "5286671" "5286976" "5288649" "5300915" "5367167" "5367194" "5431328" "5449910" "5450053" "5512748" "5534111" "5573859" "5605489" "5659195" "5701008" "5726480" "5773987" "5777328" "5789753" "5895233" "5905007" "5915168" "5919548" "5921461" "5923995" "5929441" "5970315" "6028312" "6036872" "6046067" "6054745" "6062461" "6064216" "6087199" "6119920" "6143997" "6159812" "6210988" "6232150" "6479320").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 17:00

S34	21	(seal\$4 solidif\$4) with (frame ring spacer damp interposer) and (chip ic semiconductor cis cmos) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid plate) same (vacuum suction atmosphere sucking (negative adj1 pressure)) and wafer and (frame ring spacer damp interposer) with (crack\$3 break\$3 broken collaps\$3)	USPAT; EPO; JPO	OR	ON	2005/12/08 17:19
S36	6	(frame ring spac\$3 damp interposer) same (chip ic semiconductor cis cmos) and (transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid plate) same (((vacuum atmosphere) near2 chamber) (negative adj1 pressure)) and wafer and (frame ring spac\$3 damp interposer) with (crack\$3 break\$3 broken collaps\$3)	USPAT; EPO; JPO	OR	ON	2005/12/08 17:22
S38	12	(frame ring spac\$3 damp interposer) same (chip ic semiconductor cis cmos) same (clear transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid plate) and (((vacuum atmosphere) near2 chamber) (negative near2 pressure)) and wafer and (frame ring spac\$3 damp interposer) with (crack\$3 break\$3 broken collaps\$3)	USPAT; EPO; JPO	OR	ON	2005/12/08 18:31
S39	3	(frame ring spac\$3 damp interposer) same (chip ic semiconductor cis cmos) same (clear transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid plate) and (atmosphere pressure) with (inside outside difference "the same" equal) same (frame ring spac\$3 damp interposer) with (crack\$3 break\$3 broken collaps\$3) and wafer	USPAT; EPO; JPO	OR	ON	2005/12/08 18:38
S42	6	(frame ring spac\$3 damp interposer) same (chip ic semiconductor cis cmos) same (clear transparen\$2 glass) near2 (substrate board cap housing cover\$3 lid plate) and (atmosphere pressure) with (inside outside difference "the same" equal) same (frame ring spac\$3 damp interposer) with (crack\$3 break\$3 broken collaps\$3)	USPAT; EPO; JPO	OR	ON	2005/12/08 18:40

S43	30	(frame ring spac\$3 damp interposer) same (chip ic semiconductor cis cmos) same (substrate board cap housing cover\$3 lid plate) and (atmosphere pressure) with (inside outside difference "the same" equal) same (frame ring spac\$3 damp interposer) with (crack\$3 break\$3 broken collaps\$3)	USPAT; EPO; JPO	OR	ON	2005/12/09 18:28
S45	43	(frame ring spac\$3 damp interposer) same (chip ic semiconductor cis cmos) same (substrate board cap housing cover\$3 lid plate) and (frame ring spac\$3 damp interposer) with (crack\$3 break\$3 broken collaps\$3) and (frame ring spac\$3 damp interposer) with ultraviolet	USPAT; EPO; JPO	OR	ON	2005/12/09 18:46
S46	4	(frame ring spac\$3 dam interposer) same (chip ic semiconductor cis cmos) same (substrate board cap housing cover\$3 lid plate) and (frame ring spac\$3 dam interposer) with (crack\$3 break\$3 broken collaps\$3) and (frame ring spac\$3 dam interposer) with ultraviolet not S45	USPAT; EPO; JPO	OR	ON	2005/12/09 18:48
S47	24	(frame ring spac\$3 dam interposer) same (chip ic semiconductor cis cmos) and (substrate board cap housing cover\$3 lid plate) and (frame ring spac\$3 dam interposer) with (crack\$3 break\$3 broken collaps\$3) and (frame ring spac\$3 dam interposer) with ultraviolet and (atmosphere (negative adj1 pressure))	USPAT; EPO; JPO	OR	ON	2005/12/09 18:55
S48	160	(frame ring spac\$3 dam interposer) same (chip ic semiconductor cis cmos) and (substrate board cap housing cover\$3 lid plate) and (frame ring spac\$3 dam interposer) with (crack\$3 break\$3 broken collaps\$3) and (frame ring spac\$3 dam interposer) with (atmosphere (negative adj1 pressure))	USPAT; EPO; JPO	OR	ON	2005/12/09 18:56
S49	54	(frame ring spac\$3 dam interposer) same (chip ic semiconductor cis cmos) and (substrate board cap housing cover\$3 lid plate) and (frame ring spac\$3 dam interposer) with (crack\$3 break\$3 broken collaps\$3) same (atmosphere (negative adj1 pressure))	USPAT; EPO; JPO	OR	ON	2005/12/09 19:11

S50	117	(frame ring spac\$3 dam interposer) same (chip ic semiconductor cis cmos) same (substrate board cap housing cover\$3 lid plate) and (frame ring spac\$3 dam interposer) with (crack\$3 break\$3 broken collaps\$3) same (atmosphere pa psi atm torr bar kpa mercury (negative adj1 pressure)) not S49	USPAT; EPO; JPO	OR	ON	2005/12/09 19:13
S51	15	(frame ring spacer dam interposer) near2 (around surround) with (electronic electrical chip ic semiconductor) and (transparen\$2 glass) near3 (substrate board cap housing cover\$3 lid shield plate) and (vacuum suction sucking atmosphere psi torr (negative adj1 pressure)) and wafer and ultraviolet	USPAT; EPO; JPO	OR	ON	2005/12/12 11:45
S52	5	(frame ring spacer dam interposer) near2 (around surround) with (electronic electrical chip ic semiconductor) and (transparen\$2 glass) near3 (substrate board cap housing cover\$3 lid shield plate) and (vacuum suction sucking atmosphere psi torr (negative adj1 pressure)) and wafer and (frame ring spacer dam interposer) with (cure curing cured solidif\$4) with (light ultraviolet)	USPAT; EPO; JPO	OR	ON	2005/12/12 11:49
S53	12	(frame ring spacer dam interposer) with (electronic electrical chip ic semiconductor) and (transparen\$2 glass) near3 (substrate board cap housing cover\$3 lid shield plate) and (vacuum suction sucking atmosphere psi torr (negative adj1 pressure)) and wafer and (frame ring spacer dam interposer) with (cure curing cured solidif\$4) with (light ultraviolet)	USPAT; EPO; JPO	OR	ON	2005/12/12 11:50
S54	10	("4637713" "5616927" "5693382" "5723860" "5769984" "5772817" "5772842" "5976307" "6103427" "6264773").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 14:29
S55	21	("5529959").URPN.	USPAT	OR	ON	2005/12/12 15:43
S56	8	("4400870" "4685200" "5070041" "5073521" "5173147" "5194695" "5250469" "5343076").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 15:46
S57	4	("5022725" "5111049" "5401968" "5433639").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 17:23
S58	3	("4418284" "4467342" "4523102").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 18:37